

Title (en)

Encased PCB switch assembly with contact device

Title (de)

Gehauste Halbleiterschaltungsanordnung mit Kontakteinrichtung

Title (fr)

Circuit semi-conducteur dans un boîtier doté d'un dispositif de contact

Publication

EP 1898466 A3 20080507 (DE)

Application

EP 07011533 A 20070613

Priority

DE 102006027482 A 20060614

Abstract (en)

[origin: DE102006027482B3] The arrangement has a substrate with conductive paths, and two conductive layers (60, 64) structured to form the conductive paths. The layers comprise a contact device to a joint surface of a semiconductor component (58) e.g. power diode, and a part of the conductive layers is a part of another contact device (4). The latter contact device comprises a spring unit with a support (30) in a housing (3) and a locking screw. The spring unit comprises a contact surface (402) for an external supply and another contact surface (606) for the layers.

IPC 8 full level

H01L 23/48 (2006.01); **H01R 4/30** (2006.01); **H01R 4/48** (2006.01)

CPC (source: EP)

H01L 23/041 (2013.01); **H01L 23/48** (2013.01); **H01L 25/072** (2013.01); **H01R 4/30** (2013.01); **H01R 4/4821** (2023.08); **H01R 4/4846** (2023.08); **H01R 12/61** (2013.01); **H01R 12/63** (2013.01); **H05K 3/325** (2013.01); **H05K 3/365** (2013.01); **H01L 24/32** (2013.01); **H01L 2224/0603** (2013.01); **H01L 2224/06181** (2013.01); **H01L 2224/32188** (2013.01); **H01L 2224/8384** (2013.01); **H01L 2924/14** (2013.01); **H01L 2924/16195** (2013.01); **H01L 2924/19041** (2013.01); **H01L 2924/19043** (2013.01); **H05K 1/189** (2013.01); **H05K 3/36** (2013.01); **H05K 2201/0311** (2013.01); **H05K 2201/0999** (2013.01)

Citation (search report)

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- [A] DE 3915611 C1 19900613
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Cited by

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

Designated extension state (EPC)

AL BA HR MK RS

DOCDB simple family (publication)

DE 102006027482 B3 20070816; EP 1898466 A2 20080312; EP 1898466 A3 20080507; EP 1898466 B1 20170823

DOCDB simple family (application)

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